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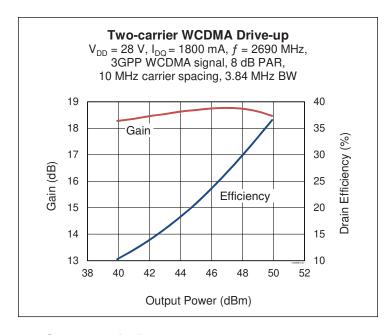




Thermally-Enhanced High Power RF LDMOS FET 280 W, 28 V, 2620 - 2690 MHz

Description

The PTFC262808SV is a 280-watt LDMOS FET intended for use in multi-standard cellular power amplifier applications in the 2620 to 2690 MHz frequency band. Features include input and output matching, high gain and thermally-enhanced package. Manufactured with Infineon's advanced LDMOS process, this device provides excellent thermal performance and superior reliability.





Features

PTFC262808SV

with formed leads

- Broadband internal matching
- Typical CW pulsed performance, 2620 MHz, 28 V
 - Output power at P_{1dB} = 280 W
 - Efficiency = 52%
 - Gain = 18 dB
- Typical 1-carrier WCDMA performance, 2655 MHz,
 - Output power at P_{1dB} = 56 W avg.
 - Efficiency = 24%
 - Gain = 18.0 dB
- Integrated ESD protection: Human Body Model, Class 1C (per JESD22-A114)
- Low thermal resistance
- RoHS-compliant
- Capable of handling 10:1 VSWR at 28 V, 280 W (CW) ouput power

RF Characteristics

Single-carrier WCDMA Specifications (tested in Infineon production test fixture)

 V_{DD} = 28 V, I_{DQ} = 1800 mA, P_{OUT} = 56 W average, f = 2655 MHz, 3GPP WCDMA signal, channel bandwidth = 3.84 MHz, peak/average = 10 dB @ 0.01% CCDF

Characteristic	Symbol	Min	Тур	Max	Unit
Gain	G_ps	16.5	18.0	_	dB
Drain Efficiency	η_{D}	22	24	_	%
Adjacent Channel Power Ratio	ACPR	_	-33	-30	dBc

All published data at $T_{CASE} = 25^{\circ}C$ unless otherwise indicated

ESD: Electrostatic discharge sensitive device—observe handling precautions!



DC Characteristics (single side)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{DS} = 10 \text{ mA}$	V _{(BR)DSS}	65	_	_	V
Drain Leakage Current	$V_{DS} = 28 \text{ V}, V_{GS} = 0 \text{ V}$	I _{DSS}	_	_	1.0	μΑ
	$V_{DS} = 63 \text{ V}, V_{GS} = 0 \text{ V}$	I _{DSS}	_	_	10.0	μΑ
On-State Resistance	$V_{GS} = 10 \text{ V}, V_{DS} = 0.1 \text{ V}$	R _{DS(on)}	_	0.05	_	Ω
Operating Gate Voltage	$V_{DS} = 28 \text{ V}, I_{DQ} = 1.45 \text{ A}$	V_{GS}	_	2.65	_	V
Gate Leakage Current	$V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V}$	I _{GSS}	_	_	1	μΑ

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	65	V
Gate-Source Voltage	V_{GS}	-6 to +10	V
Operating Voltage	V_{DD}	0 to +32	V
Junction Temperature	ТЈ	200	°C
Storage Temperature Range	T _{STG}	-65 to +150	°C
Thermal Resistance (T _{CASE} = 70°C, 200 W CW)	$R_{ hetaJC}$	0.20	°C/W

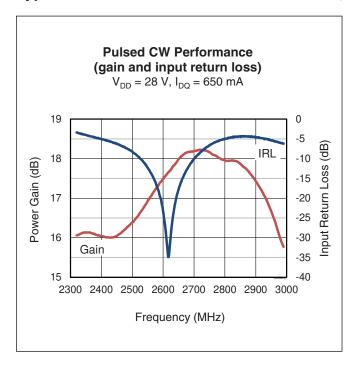
Ordering Information

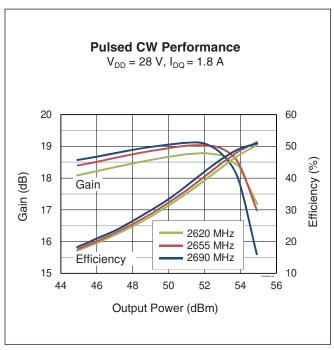
Type and Version	Order Code	Package and Description	Shipping
PTFC 262808SV V1 R250	PTFC262808SVV1R250XTMA1	H-37275G-6/2, ceramic open-cavity, formed leads,	Tape & Reel, 250 pcs
		earless	

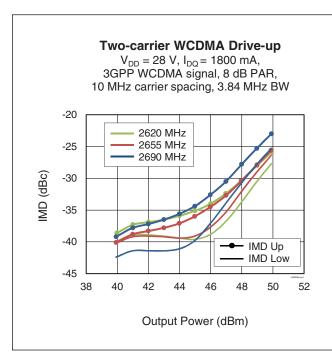
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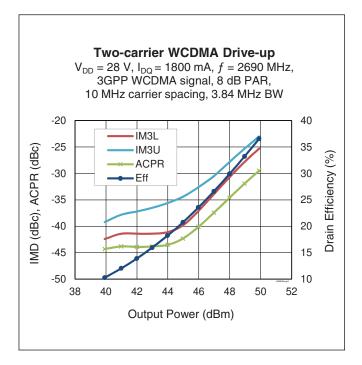


Typical Performance (data taken in a reference design fixture)



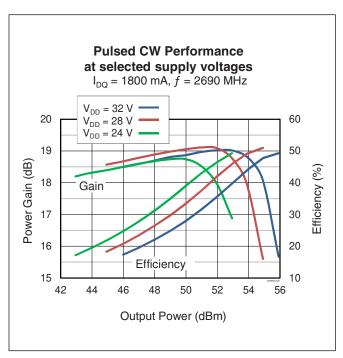






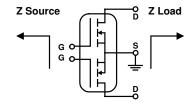


Typical Performance (cont.)



Broadband Circuit Impedance

Frequency	Z Source Ω		Z Lo	ad Ω
MHz	R	jΧ	R	jΧ
2620	2.07	-2.45	0.69	-4.22
2655	1.98	-2.39	0.68	-4.19
2690	1.91	-2.33	0.66	-4.08

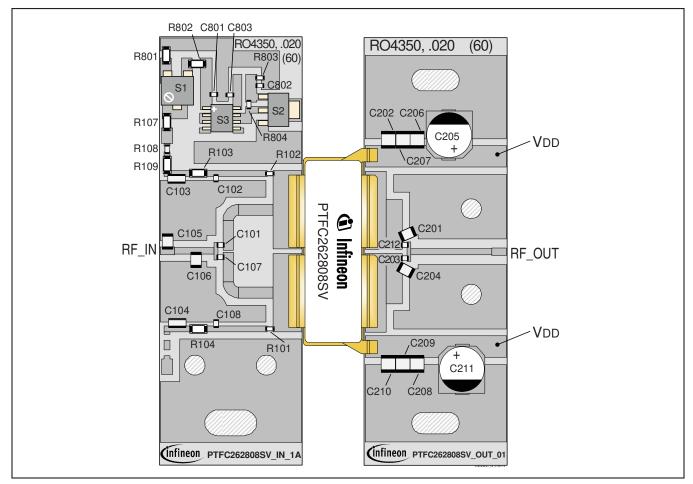




Reference Circuit, tuned for 2620 - 2690 MHz

DUT	PTFC262808SV
Test Fixture Part No.	LTN/PTFC262808SV V1
PCB	Rogers 4350, 0.508 mm [.020"] thick, 2 oz. copper, ε_{r} = 3.66

Find Gerber files for this test fixture on the Infineon Web site at (http://www.infineon.com/rfpower)



Reference circuit assembly diagram (not to scale)

Cam	non	ont	Infor	mation
Com	non	ent	intor	mation

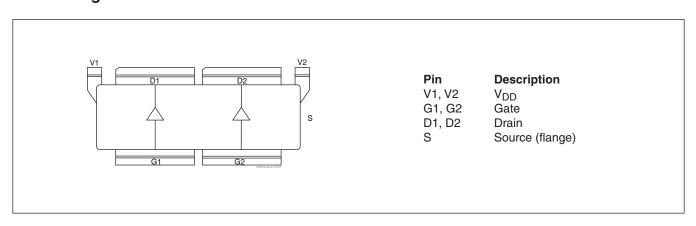
Component information				
Component	Description	Suggested Manufacturer	P/N	
Input				
C101, C102, C107, C108	Chip capacitor, 18 pF	ATC	ATC800A180JW250X	
C103, C104	Capacitor, 10 µF	Murata Electronics North America	LLL31BC70G106MA01L	
C105	Chip capacitor, 0.4 pF	ATC	ATC100B0R4CW150X	
C106	Chip capacitor, 0.7 pF	ATC	ATC100B0R7CW150X	
C801, C802, C803	Chip capacitor, 1,000 pF	Panasonic Electronic Components	ECJ-1VB1H102K	
R101, R102	Resistor, 10 Ω	Panasonic Electronic Components	ERJ-3GEYJ100V	



Reference Circuit (cont.)

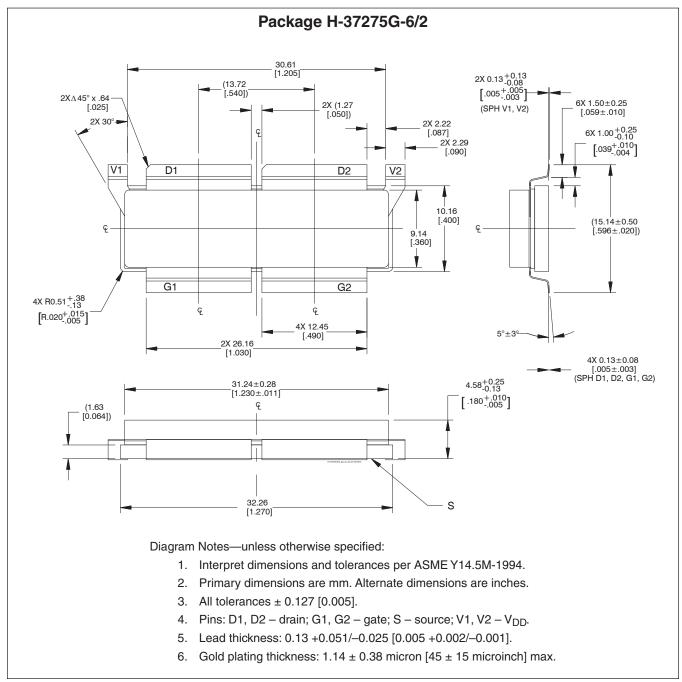
Component Information (cont.)				
Component	Description	Suggested Manufacturer	P/N	
Input (cont.)				
R103, R104	Resistor, 10 Ω	Panasonic Electronic Components	ERJ-8GEYJ100V	
R107, R109	Resistor, 0.0 Ω	Panasonic Electronic Components	ERJ-8GEY0R00V	
R108	Resistor, 0.0 Ω	Panasonic Electronic Components	ERJ-3GEY0R00V	
R801	Resistor, 1 Ω	Panasonic Electronic Components	ERJ-8GEYJ1R0V	
R802	Resistor, 1k Ω	Panasonic Electronic Components	ERJ-8GEYJ102V	
R803	Resistor, 1.3k Ω	Panasonic Electronic Components	ERJ-3GEYJ132V	
R804	Resistor, 1.2k Ω	Panasonic Electronic Components	ERJ-3GEYJ122V	
S1	Potentiometer, 2k Ω	Bourns Inc.	3224W-1-202E	
S2	Transistor	Infineon Technologies	BCP56-10	
S3	Voltage regulator	Fairchild Semiconductor	LM7805	
Output				
C201, C204	Chip capacitor, 0.2 pF	ATC	ATC100B0R2BW150X	
C202, C206, C207, C208,	Capacitor, 10 μF	Taiyo Yuden	UMK325C7106MM-T	
C209, C210				
C203, C212	Chip capacitor, 18 pF	ATC	ATC800A180JW250X	
C205, C211	Capacitor, 220 µF, 35 V	Panasonic Electronic Components	EEE-FP1V221AP	

Pinout Diagram





Package Outline Specifications



Find the latest and most complete information about products and packaging at the Infineon Internet page (http://www.infineon.com/rfpower)

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PTFC262808SV V1

Revision History:	2013-08-02	Data Sheet
Previous Version:	2013-07-24, Data Sheet; 2012-08-09, Advance Specification	
Page	Subjects (major changes since last revision)	
all	Product released to production, information complete and current.	
1, 2, 6	Typos corrected.	

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